



100% Material Declaration Data Sheet for 7 Series FFG901

PK550 (v1.1) January 25, 2013

Average Weight: 10.1290g

Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Silicon Die					0.446519	4.408
	Silicon (Si)	7440-21-3	100.00	Basis	0.446519	
Solder Bump					0.029370	0.290
	Tin (Sn)	7440-31-5	63.00	Basis	0.018503	
	Lead (Pb)	7439-92-1	37.00	Basis	0.010867	
Solder Paste					0.071000	0.701
	Tin (Sn)	7440-31-5	96.50	Basis	0.068515	
	Silver (Ag)	7440-22-4	3.00	Basis	0.002130	
	Copper (Cu)	7440-50-8	0.50	Basis	0.000355	
Capacitor 1					0.037800	0.373
	BaTiO3 type	12047-27-7	70.60	Ceramic	0.026687	
	Nickel (Ni)	7440-02-0	6.70	Inner electrode	0.002533	
	Copper (Cu)	7440-50-8	20.10	Outer electrode	0.007598	
	Nickel (Ni)	7440-02-0	0.80	Plating 1	0.000302	
	Tin (Sn)	7440-31-5	1.80	Plating 2	0.000680	
Capacitor 2					0.007360	0.073
	BaTiO3 type	12047-27-7	51.10	Ceramic	0.003761	
	Nickel (Ni)	7440-02-0	27.00	Inner electrode	0.001987	
	Copper (Cu)	7440-50-8	16.00	Outer electrode	0.001178	
	Glass	65997-17-3	0.90		0.000066	
	Nickel (Ni)	7440-02-0	2.00	Plating 1	0.000147	
	Tin (Sn)	7440-31-5	3.00	Plating 2	0.000221	
Capacitor 3					0.004200	0.041
	BaTiO3 type	12047-27-7	66.00	Ceramic	0.002772	
	Nickel (Ni)	7440-02-0	2.67	Inner electrode	0.000112	
	Copper (Cu)	7440-50-8	23.33	Outer electrode	0.000980	
	Nickel (Ni)	7440-02-0	2.33	Plating 1	0.000098	
	Tin (Sn)	7440-31-5	5.67	Plating 2	0.000238	

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Component	Substance Description	CAS Number or Description	Percentage of Component	Use in Product	Component Weight/ Substance Weight (grams)	Component Percent of Total
Underfill					0.053000	0.523
	Bisphenol F/ epichlorohydrin copolymer	9003-36-5	20.00	Basis	0.010600	
	Phenolic Resin	Trade Secret	15.00	Basis	0.007950	
	Bisphenol A type liquid epoxy resin	25068-38-6	5.00	Basis	0.002650	
	Amine type accelerator	Trade Secret	5.00	Basis	0.002650	
	Silicon Dioxide	60676-86-0	51.50	Basis	0.027295	
	Carbon Black	1333-86-4	1.00	Basis	0.000530	
	Additives	Trade Secret	2.50	Additive	0.001325	
Lid Adhesive					0.103000	1.017
	Aluminum Oxide Al ₂ O ₃	1344-28-1	70.00	Basis	0.072100	
	Dimethyl siloxane, dimethylvinyl-terminated	68083-19-2	30.00	Basis	0.030900	
Lid					5.818000	57.439
	Copper (Cu)	7440-50-8	99.12	Main Material	5.766802	
	Nickel (Ni)	7440-02-0	0.88	Main Material	0.051198	
Solder Ball					0.751829	7.423
	Tin (Sn)	7440-31-5	96.50	Main Material	0.725515	
	Silver (Ag)	7440-22-4	3.00	Main Material	0.022555	
	Copper (Cu)	7440-50-8	0.50	Main Material	0.003759	
Substrate					2.806923	27.712
	Copper (Cu)	7440-50-8	41.023		1.151484	
	Tin (Sn)	7440-31-5	0.832		0.023354	
	Lead (Pb)	7439-92-1	0.173		0.004856	
	Silver (Ag)	7440-22-4	0.017		0.000477	
	BT Core	N/A	44.059		1.236702	
	ABF	N/A	11.602		0.325659	
	Solder Mask	N/A	2.294		0.064391	

Revision History

The following table shows the revision history for this document.

Date	Version	Description of Revisions
06/06/2012	1.0	Initial Xilinx release.
01/25/2013	1.1	Update substrate component.

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